



T-1 3/4 (5mm) SOLID STATE LAMP

Features

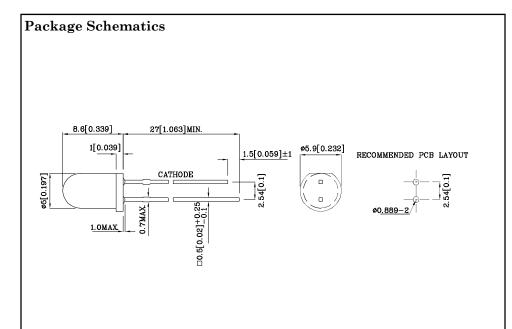
- Radial / Through hole package
- \bullet Reliable & robust
- Low power consumption
- Available on tape and reel
- 14V internal resistor.
- RoHS Compliant







ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T_A =25°C)		MDK (AlGaInP)	Unit		
Reverse Voltage	V_{R}	5	V		
Forward Voltage	V_{F}	16	V		
Power Dissipation	P_D	160	mW		
Operating Temperature	T _A -40 ~ +70		°C		
Storage Temperature	Tstg	-40 ~ +85			
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

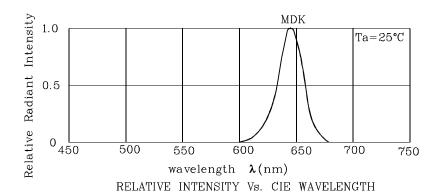
Operating Characteristics $(T_A=25^{\circ}C)$		MDK (AlGaInP)	Unit
Forward Current (Typ.) (V _F =14V)	I_{F}	10.5	mA
Forward Current (Max.) (V _F =14V)	I_{F}	13.5	mA
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (V _F =14V)	λP	645*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (V _F =14V)	λD	630*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (V _F =14V)	Δλ	28	nm

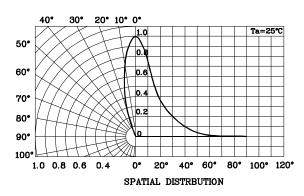
Part Number	Emitting Color	Emitting Material	Lens-color	$\begin{array}{c} Luminous\ Intensity\\ CIE127\text{-}2007*\\ (V_F\text{=}14V)\\ mcd \end{array}$		Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XLMDK12D14V	Red	AlGaInP	Red Diffused	160 50*	297 98*	645*	30°

^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

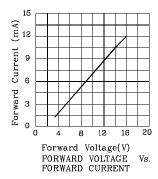


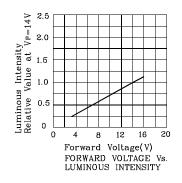


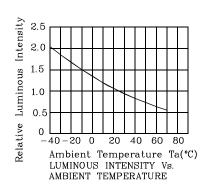




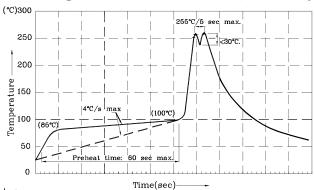
♦ MDK







Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on Luminous intensity/ luminous flux, or wavelength),

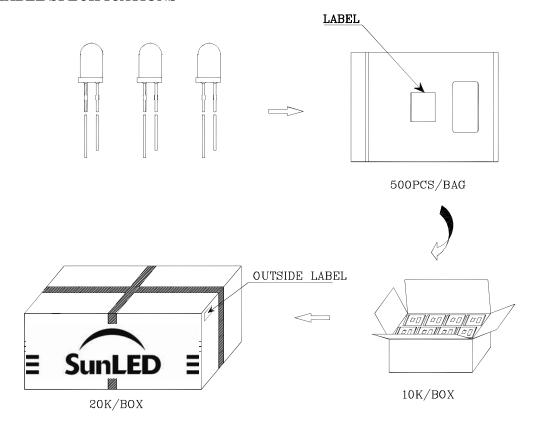
the typical accuracy of the sorting process is as follows:

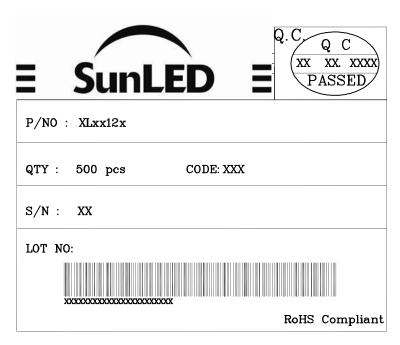
- 1. Wavelength: +/-1nm
- 2. Luminous intensity/ luminous flux: +/-15%

Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS





TERMS OF USE

- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet. User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp

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